

Title (en)
METHOD OF ATTACHING INTEGRATED CIRCUIT DIES BY ROLLING ADHESIVES ONTO SEMICONDUCTOR WAFERS

Title (de)
VERFAHREN ZUR BEFESTIGUNG VON IC-CHIPS DURCH ABROLLEN VON KLEBSTOFF AUF HALBLEITERWAFER

Title (fr)
PROCEDE DE FIXATION DE PUCES DE CIRCUIT INTEGRE CONSISTANT A APPLIQUER A L'AIDE D'UN CYLINDRE DES ADHESIFS SUR DES TRANCHES DE SEMI-CONDUCTEURS

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Application
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Abstract (en)
[origin: WO9613066A1] A method of attaching an integrated circuit die (182) to a support surface (188) is disclosed. An adhesive (164) is rolled onto a surface of a semiconductor wafer (160) using a roller to form an adhesive coating (164) on the semiconductor wafer surface. The adhesive coating (164) is dried, and the semiconductor wafer (160) is diced to form several integrated circuit dies (182) each having an integrated circuit and an adhesive layer (184) that constitutes a portion of the adhesive coating. One of the dies (182) is attached to a die attach pad (188) by placing the die's adhesive layer (184) in contact with the pad (188) which is then cured. A packaged integrated circuit (180) containing a die (182) with an adhesive layer (184) is also described.

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